

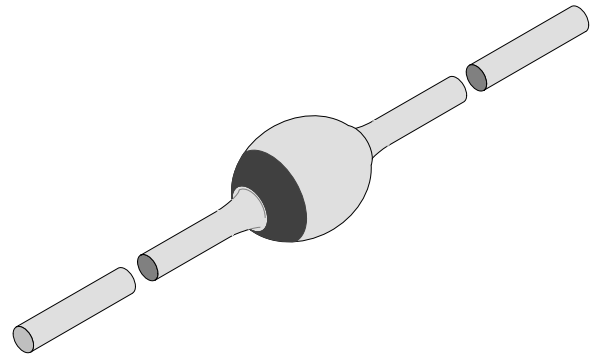
Fast Silicon Mesa Rectifiers

Features

- Glass passivated junction
- Hermetically sealed package
- Low reverse current
- Soft recovery characteristics

Applications

Very fast rectifiers and switches



94 9539

Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage, peak reverse voltage		BYT54A	$V_R=V_{RRM}$	50	V
		BYT54B	$V_R=V_{RRM}$	100	V
		BYT54D	$V_R=V_{RRM}$	200	V
		BYT54G	$V_R=V_{RRM}$	400	V
		BYT54J	$V_R=V_{RRM}$	600	V
		BYT54K	$V_R=V_{RRM}$	800	V
		BYT54M	$V_R=V_{RRM}$	1000	V
Peak forward surge current	$t_p=10\text{ms}$		I_{FSM}	30	A
Average forward current	Fig. 1		I_{FAV}	0.75	A
	$l=10\text{mm}, T_L=25^\circ\text{C}$		I_{FAV}	1.25	A
Junction temperature		BYT54A..BYT54K	T_j	175	$^\circ\text{C}$
		BYT54M	T_j	165	$^\circ\text{C}$
Storage temperature range		BYT54A..BYT54K	T_{stg}	-65...+175	$^\circ\text{C}$
		BYT54M	T_{stg}	-65...+165	$^\circ\text{C}$

Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	$l=10\text{mm}, T_L=\text{constant}$	R_{thJA}	45	K/W
	on PC board with spacing 25mm	R_{thJA}	100	K/W

Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=1\text{A}$		V_F			1.5	V
Reverse current	$V_R=V_{RRM}$		I_R			5	μA
	$V_R=V_{RRM}, T_j=150^\circ\text{C}$		I_R			150	μA
Reverse recovery time	$I_F=0.5\text{A}, I_R=1\text{A}, i_R=0.25\text{A}$		t_{rr}			100	ns

Typical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)

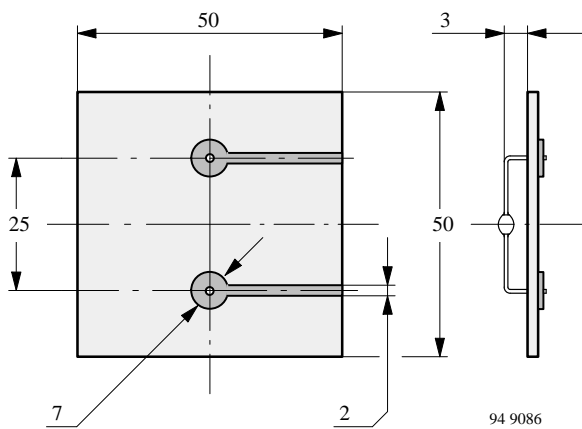


Figure 1 : Epoxy glass hard tissue, board thickness 1.5 mm,
 $R_{thJA} \leq 100 \text{ K/W}$

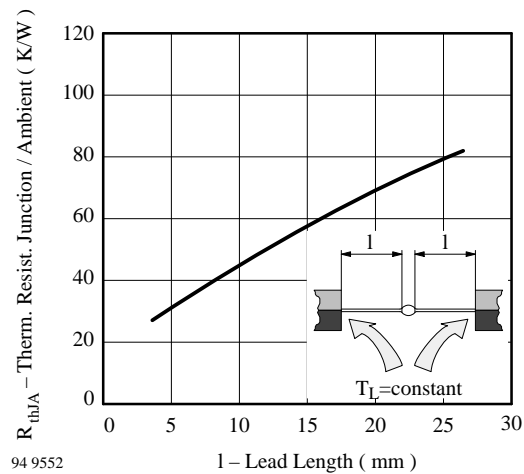


Figure 2 : Thermal Resistance vs. Lead Length

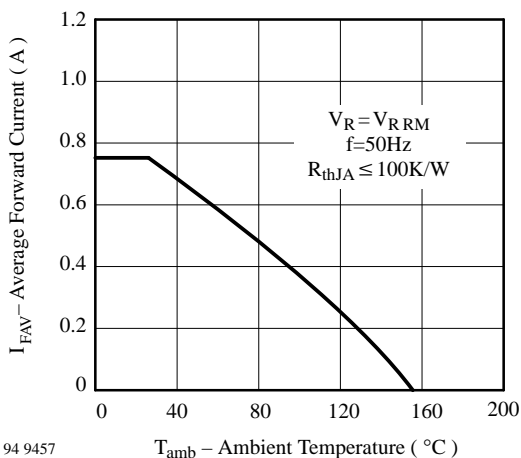


Figure 3 : Average Forward Current vs. Ambient Temperature

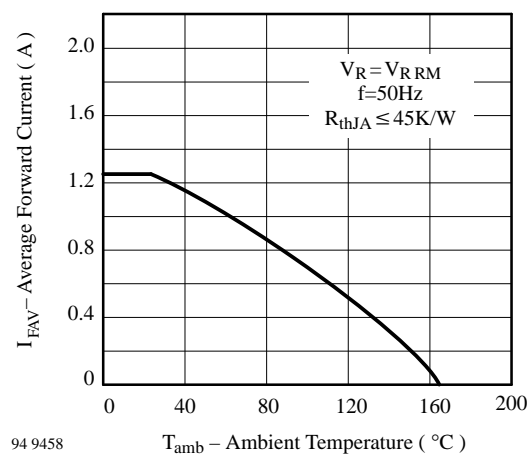


Figure 4 : Average Forward Current vs. Ambient Temperature

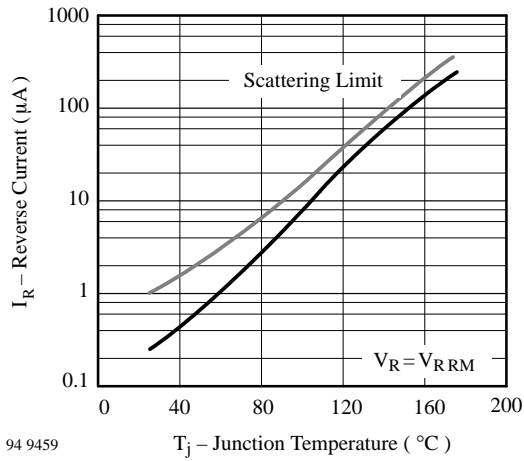


Figure 5 : Reverse Current vs. Junction Temperature

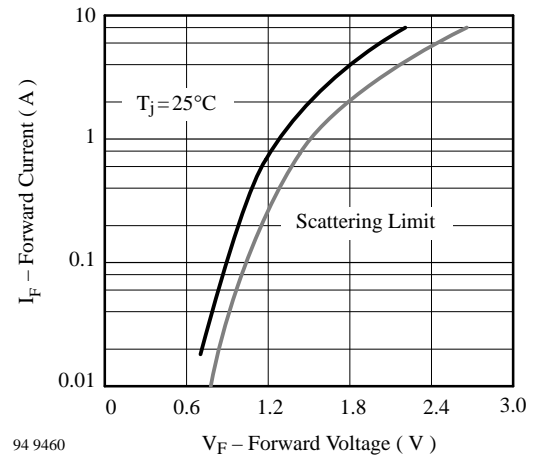


Figure 6 : Forward Current vs. Forward Voltage

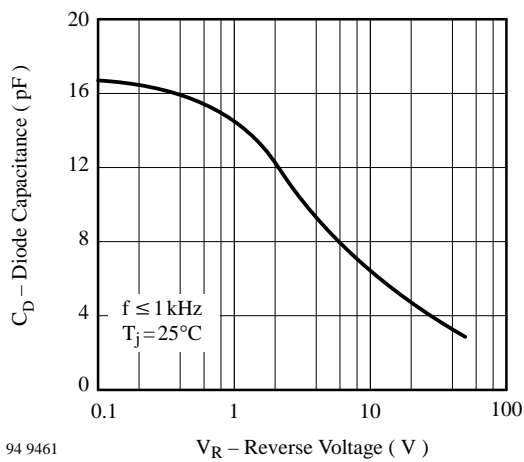
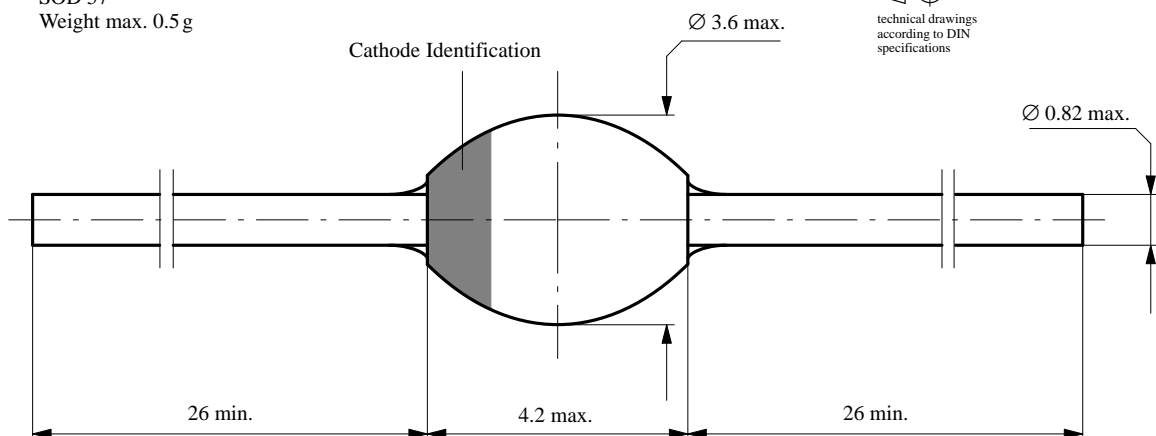


Figure 7 : Diode Capacitance vs. Reverse Voltage

Dimensions in mm

Sintered Glass Case
SOD 57
Weight max. 0.5 g



OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements and
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

Of particular concern is the control or elimination of releases into the atmosphere of those substances which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) will soon severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of any ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA and
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with and do not contain ozone depleting substances.

We reserve the right to make changes to improve technical design without further notice.

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